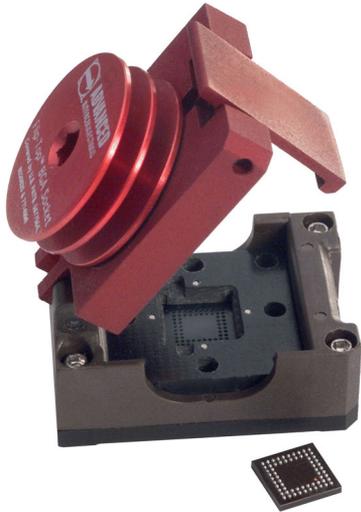
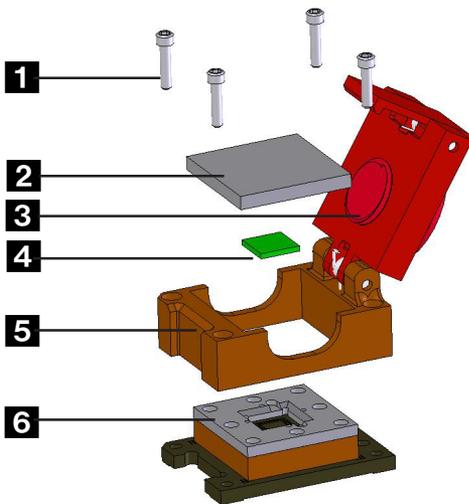


Mod5 Series 0.50mm Pitch Flip-Top™ BGA Socket



Components



1. #0-80 screws (four supplied)
2. Chip support plate
3. Turn-screw heat sink
4. BGA device (not supplied)
5. Upper assembly
6. Lower assembly

Installation

STEP 1

Place the Flip-Top™ BGA Socket lower assembly onto PC board using the chamfer as A1 pin location (see Fig. 1).

For SMT Plus (terminal mounting types -862 & -863) and SMT/Screw Mount models (terminal mounting types -864 & -865), reflow lower assembly to PC board. **For SMT Standard model (terminal mounting types -860 & -861), see note below prior to reflow.**

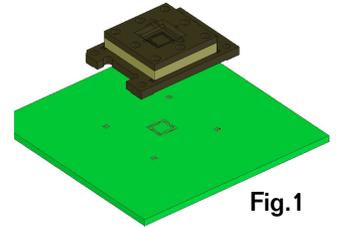


Fig.1

SMT Standard Option Note:

Before reflow: apply an epoxy (i.e. Loctite® CHIPBONDER® 348™) on the lower assembly as shown before placement on PCB and prior to soldering. Gently depress wafer stack manually, onto PCB footprint. [See Fig. 1 a]

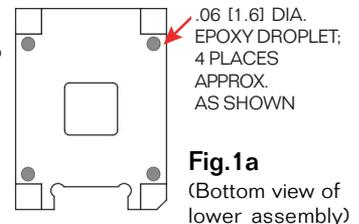


Fig.1a
(Bottom view of lower assembly)

SMT/Screw Mount Option Note:

After reflow: fasten socket through opposite side of PCB (use .067" dia. clearance holes) with #0-80 screws and washers provided, into tapped holes as shown. Tighten to 1.20 lb-in with a .050" (CF) hex drive; do not over tighten. [See Fig. 1b]

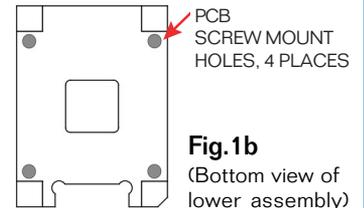


Fig.1b
(Bottom view of lower assembly)

See Application Specification (available online) or part number specific CAD drawing for board layout recommendations.

STEP 2

Align the Flip-Top BGA Socket upper assembly and lower assembly using the chamfer as a guide (see Fig. 2). Guide posts on upper assembly should be inserted into holes on lower assembly.

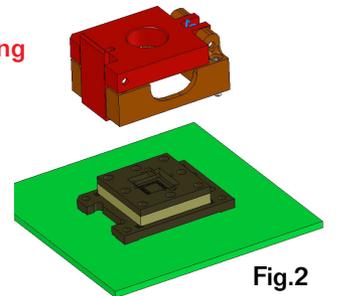


Fig.2

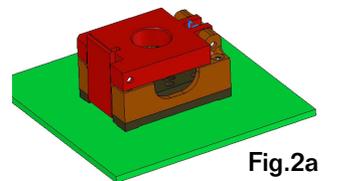


Fig.2a

Light pressure is required to "seat" the upper assembly to the lower assembly (see Fig. 2a).



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Usage

After Installation

1. Place BGA device into opened Flip-Top BGA Socket, aligning the A1 position on the BGA with the chamfered corner of the Flip-Top BGA Socket. Use of vacuum suction pen/tool is recommended.
2. Insert support plate with the extended square ram side toward the BGA device.
3. Close lid, making sure the latch is firmly engaged.
4. Tighten turn-screw heat sink in a clockwise direction until it just makes contact with the support plate. This may be done by hand or with a 1/8" hex drive (supplied).
5. Past this initial contact point, turn the turn-screw heat sink 90°-110° (approx 1.0 lb-in); for the largest position counts, turn to 110°-135° (approx 3 lb-in *MAX*). **Over tightening of turn-screw heat sink may result in damage.**
6. Socket is now ready for operation.

Additional Info

BGA Device Removal

1. Loosen turn-screw heat sink until support plate moves freely. **To avoid damage to the socket, do not attempt to open the lid until the turn-screw heat sink has been loosened.**
2. Press latch mechanism. Refer to figure 4a in Step 4.
3. After lid is opened, remove the support plate and set aside.
4. Remove BGA device. Use of vacuum suction pen/tool is recommended.

Installation

STEP 3

Install supplied #0-80 screws in rear of socket as shown in Fig. 3 and tighten using the supplied hex wrench (recommended torque value is 1.20 lb-in).

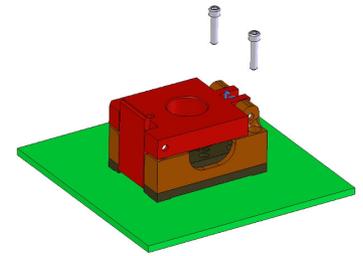


Fig.3

STEP 4

Open lid by pressing upper portion of latch mechanism back toward socket (see Fig. 4 and 4a).

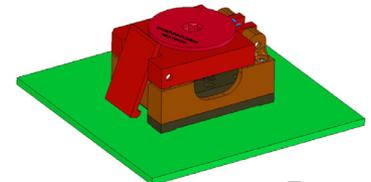


Fig.4

Lid will open approximately 115°, allowing access to the front two screw locations and allowing for device insertion (see Fig. 4b).

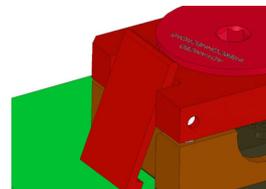


Fig.4a

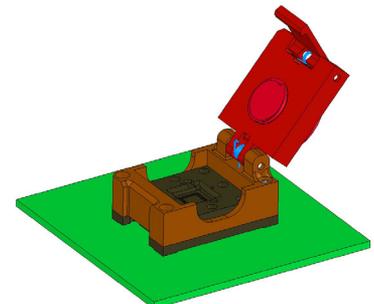


Fig.4b

STEP 5

Install supplied #0-80 screws, as shown in Fig. 5, and tighten using the supplied hex wrench recommended torque value is 1.20 lb-in).

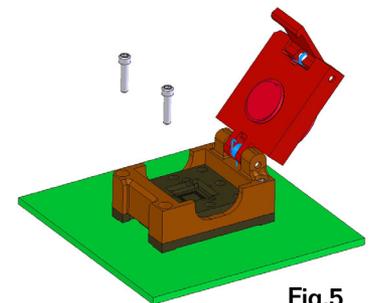


Fig.5



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